
MEMS

its methods and applications

CHE 384T – Graduate Student Presentation

11/14/17

Ji Yeon Kim
The Department of Chemical Engineering
The University of Texas at Austin



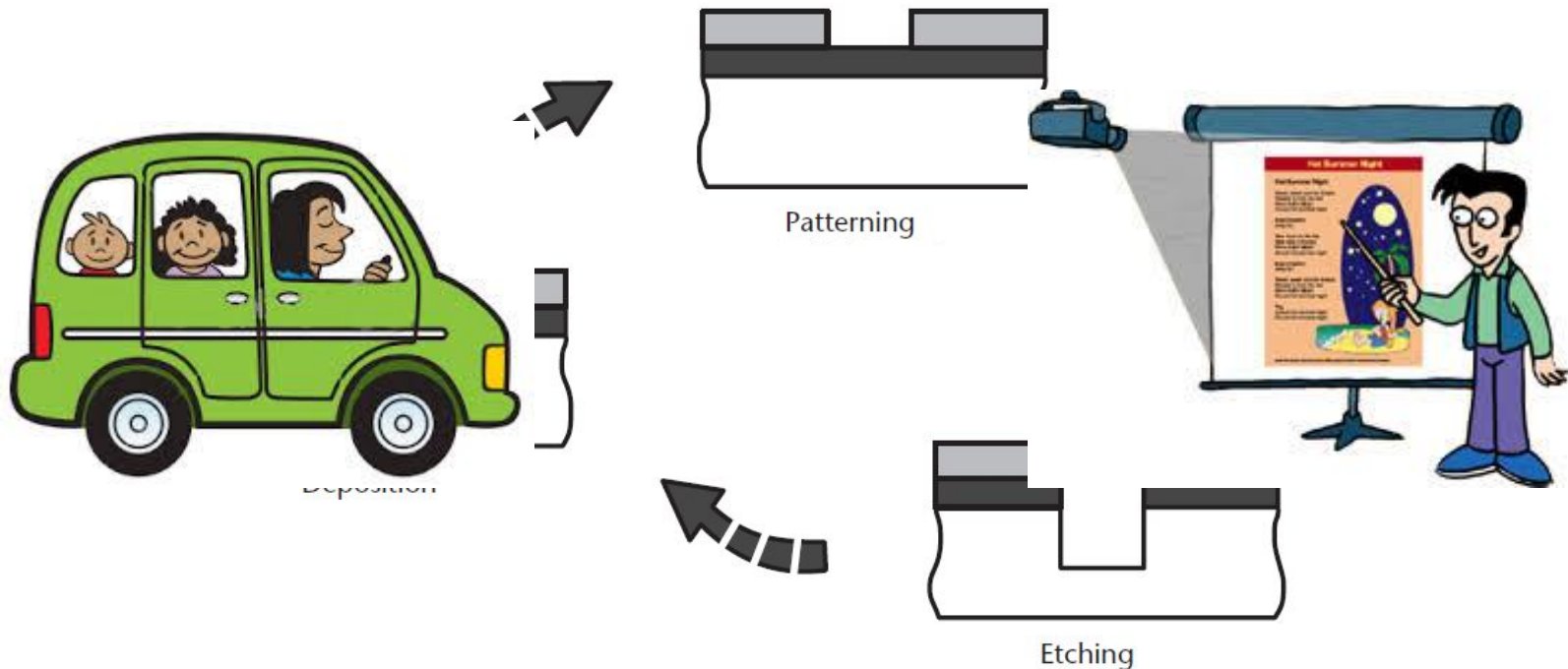
Contents

- MEMS
- Brief history
- Methods
 - Surface
 - Bulk
 - LIGA
- Applications
 - Industrial & automotive
 - Optical displays
- Outlook



MEMS - MicroElectroMechanical Systems

- A portfolio of various micromachining techniques & processes to create miniature systems at microscale
- MEMS devices are everywhere





Early days of MEMS

- Discovery of the piezoresistive effect in silicon by C.S Smith (1954)
 - A change in the electrical resistivity when mechanical strain is applied
- “Silicon as a mechanical material” by Kurt Peterson at IBM (1980s)
 - Pressure sensors, accelerometers, nozzles





Various methods of MEMS

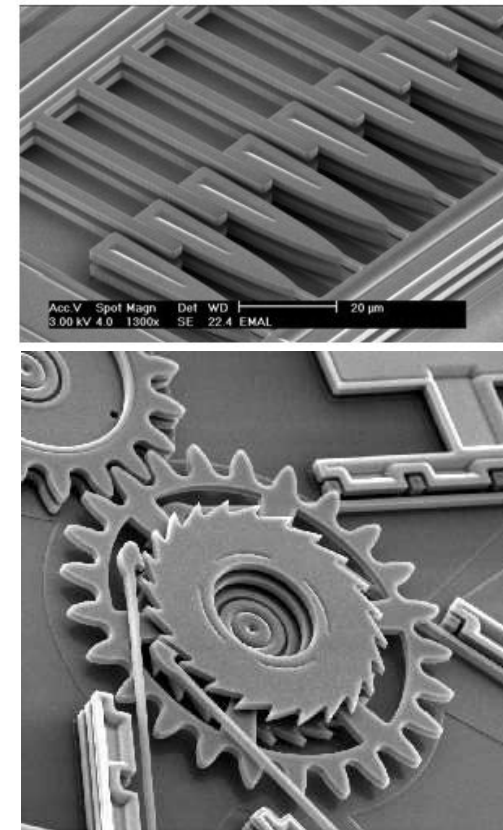
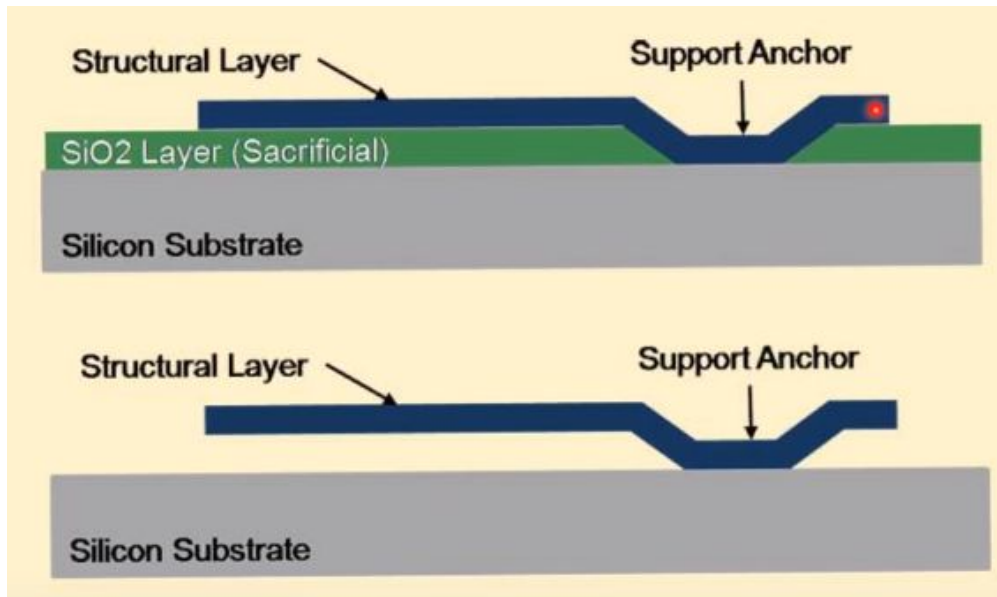
- Surface micromachining
- Bulk micromachining
- **LIGA**





1 / Surface micromachining

- Structural and sacrificial layers
- Low aspect ratio

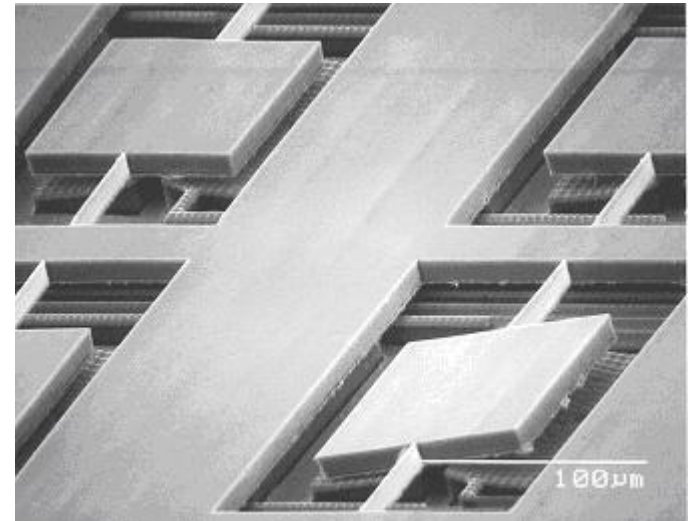
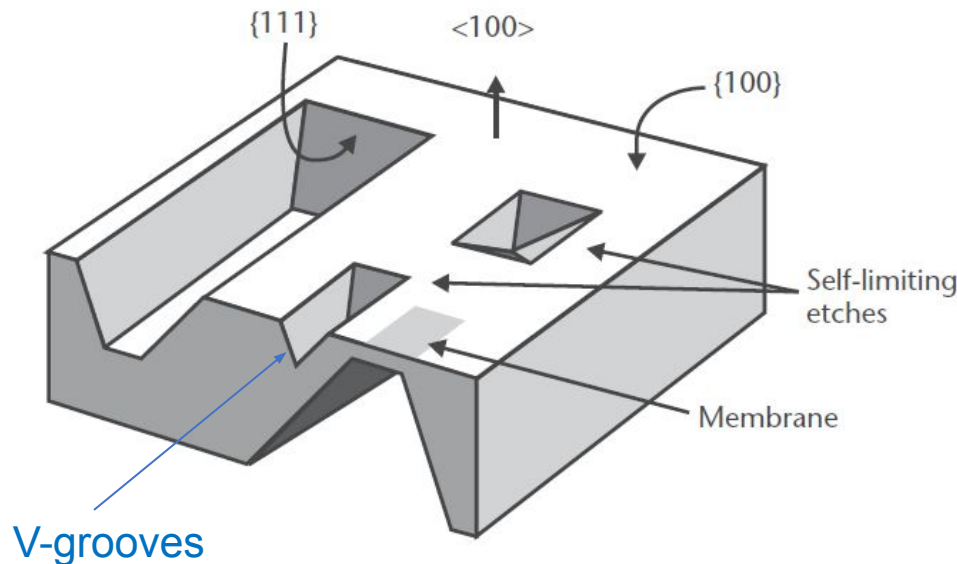




2 / Bulk micromachining

- Subtractive process
- Selective (or anisotropic) etching
 - Wet chemical etching
 - Dry plasma etching
- Higher aspect ratio

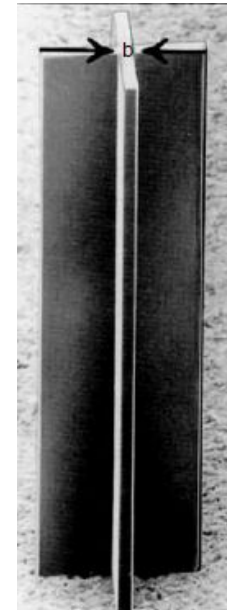
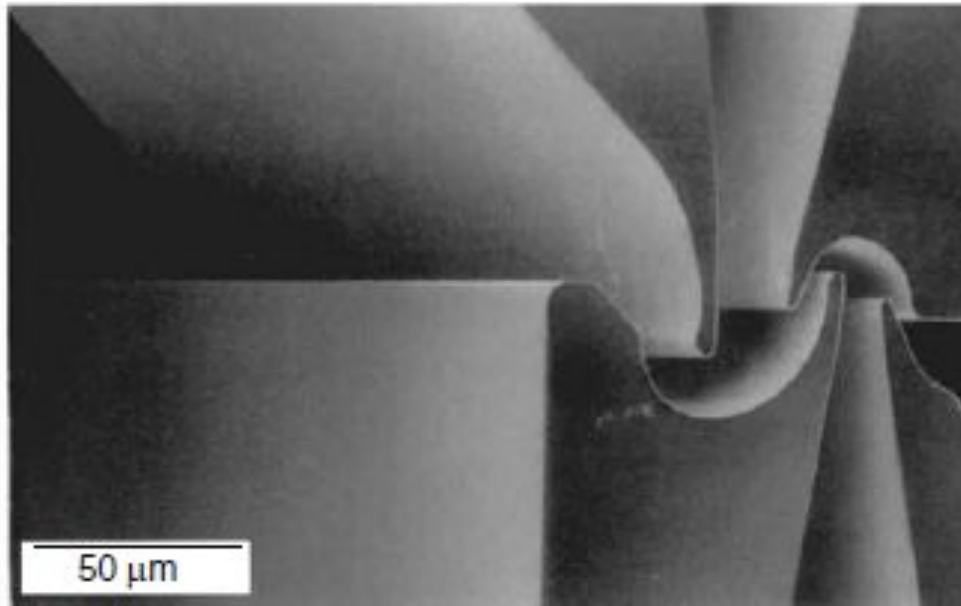
Eg) KOH etch rate: $\{110\} > \{100\} > \{111\}$





3 / LIGA – Lithographie, Galvanoformung, Abformung

- Originally studied for the mass production of micron-sized nozzles for uranium isotopes
- Additive process
- Very high aspect ratio (~ 100)
- Vertical & smooth sidewalls

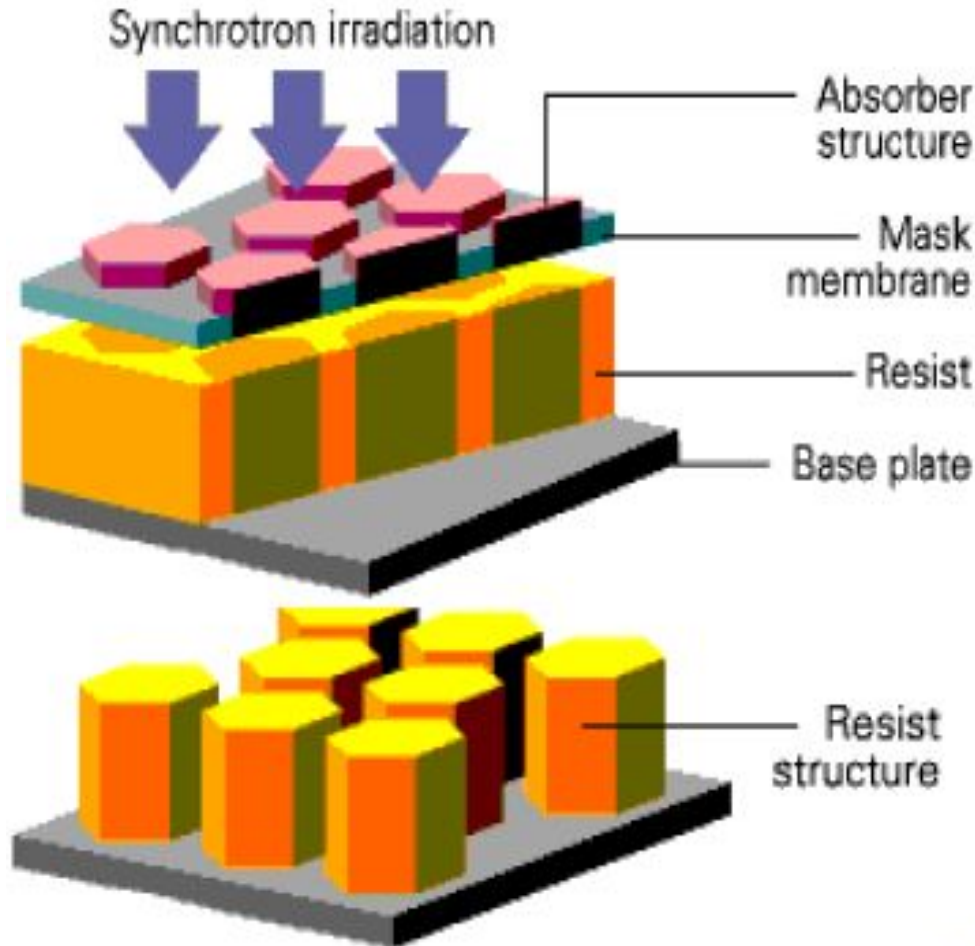


Early 1980s – Karlsruhe nuclear research center in Germany



3 / LIGA – Lithography Step

- X-ray proximity printing

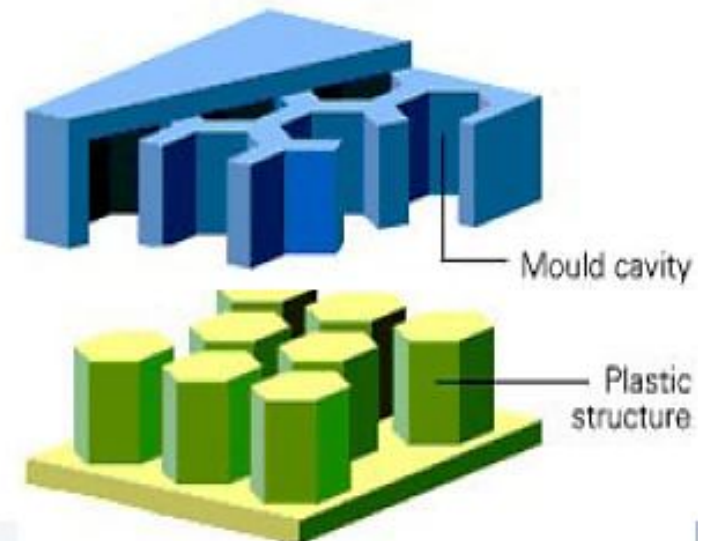
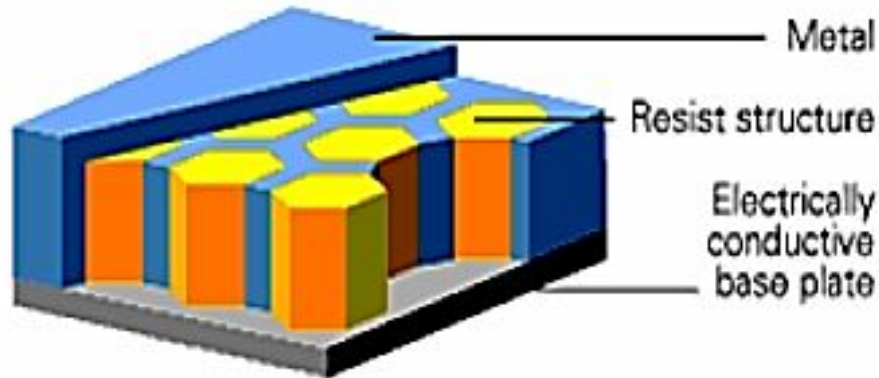


- X-ray mask
 - Thick absorber patterns and thin membrane layer
- Resist
 - PMMA
- Base plate
 - Conducting seed layer (gold/nickel)



3 / LIGA – Electroplating & Molding Step

- Immersing in electrolyte baths (e.g. Ni-sulfamate bath)
- Hot embossing/Injection molding
- Demolding with the help of mold release agents (e.g. 3-6 wt% PAT 665) & design shapes





3 / LIGA – Making a mold insert for plastic molding

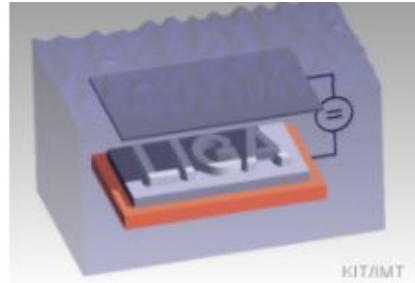


Fig. 29: Nickel electroplating in process

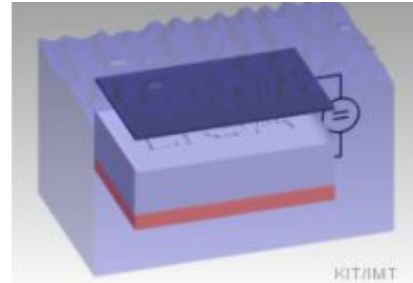


Fig. 30: Nickel electroplating finished

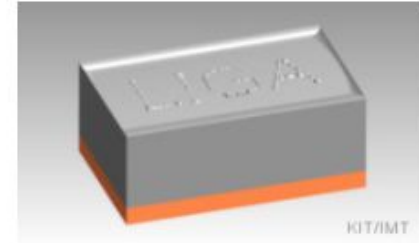


Fig. 31: Nickel mould after electroplating

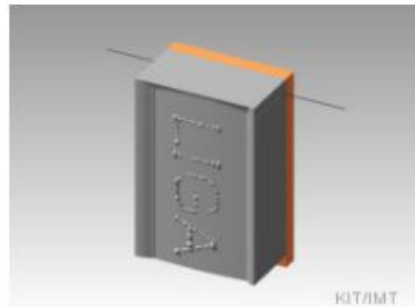


Fig. 32: Wire eroding of the mould, step 1

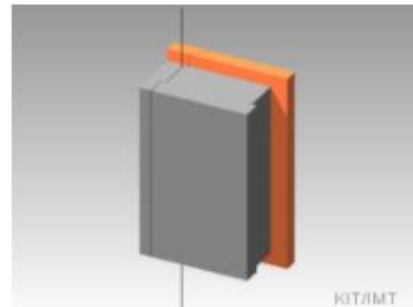


Fig. 33: Wire eroding of the mould, step 2

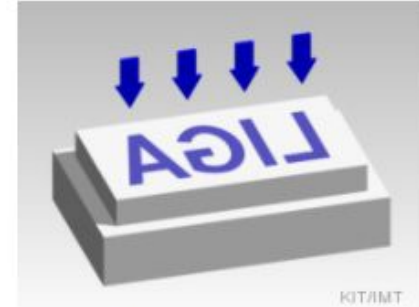


Fig. 34: Flood exposure before resist removing

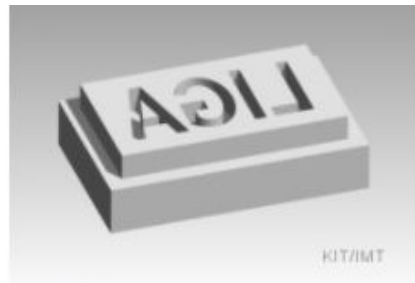


Fig. 35: Finished nickel mould



Fig. 36: Moulding for mass replication

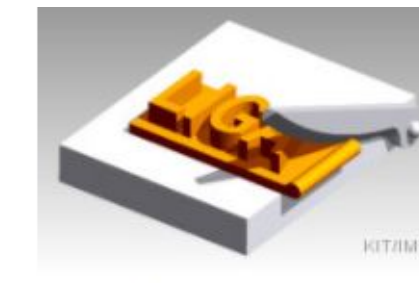
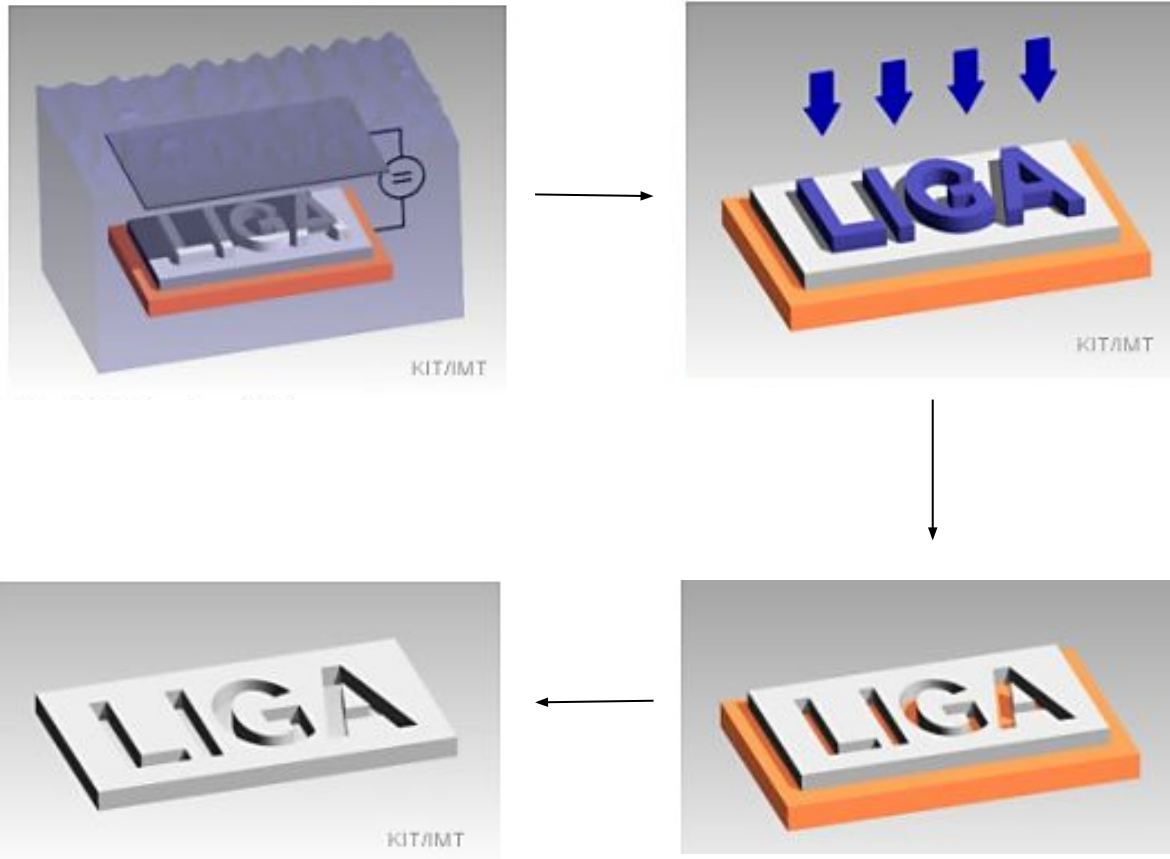


Fig. 37: Final machine finishing



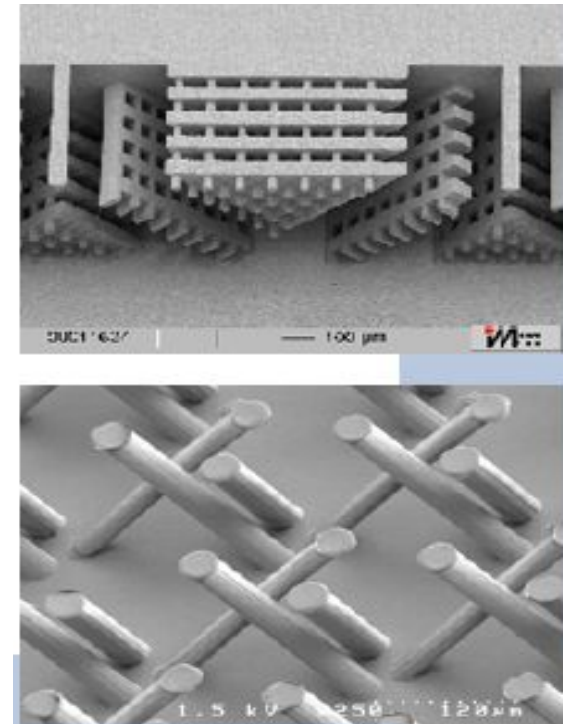
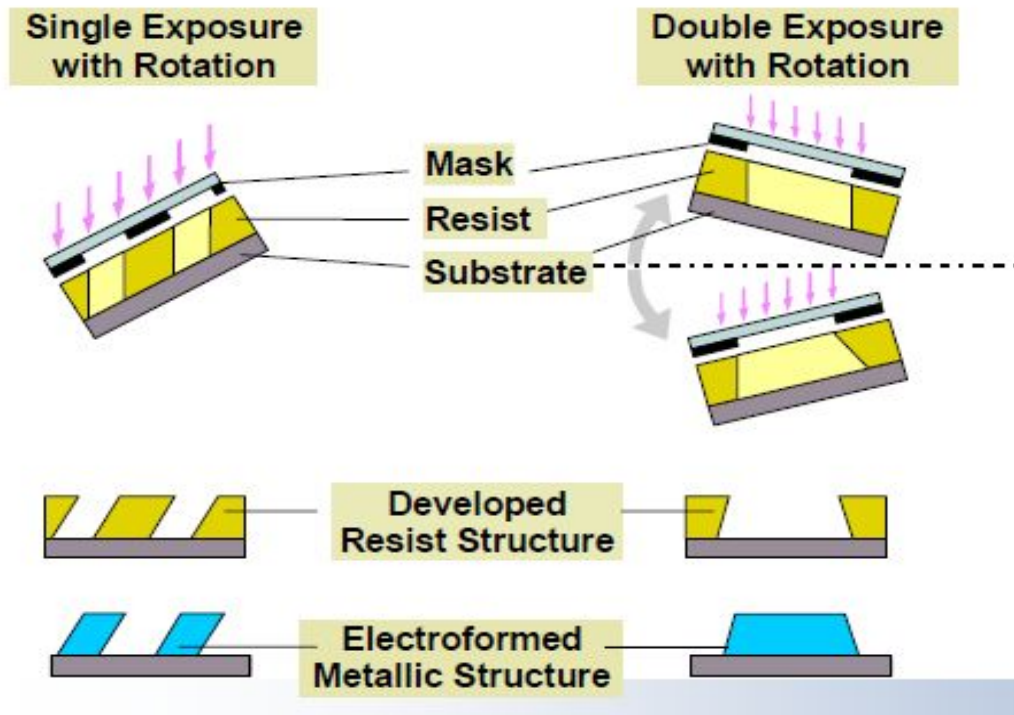
3 / LIGA – Making a microstructure





3 / LIGA – Slanted Microstructures

- Complex structures can be fabricated by multiple oblique irradiation





Various applications of MEMS

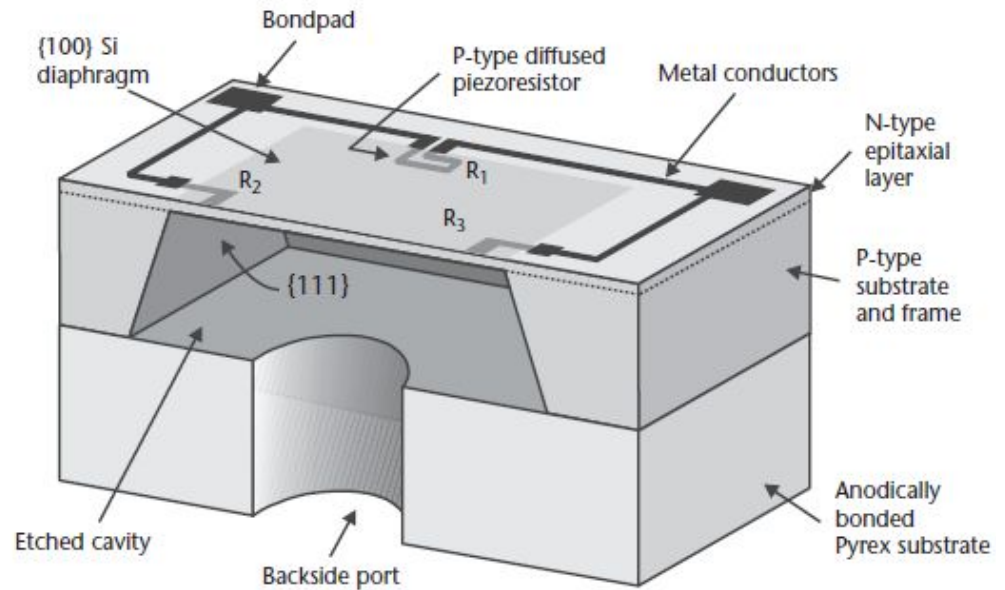
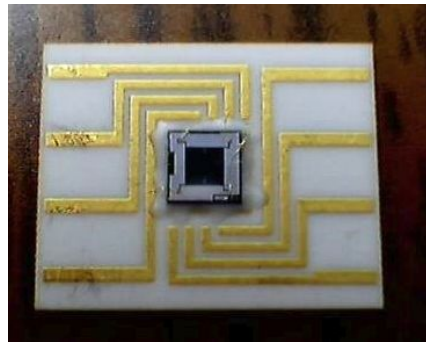
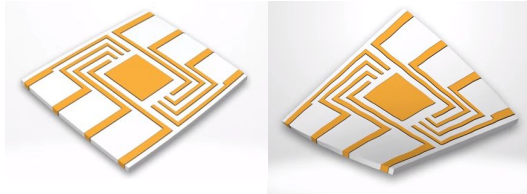
- Industrial & automotive
 - Pressure sensors
 - Accelerometers
 - Nozzles
 - Safety devices for nuclear weapons
- Optical displays
 - Digital micromirrors



1 / Industrial & automotive

• Piezoresistive pressure sensors

- Thin silicon diaphragm
- Mechanical stress causes changes in crystal lattice structure $\square$ electrical resistance changes

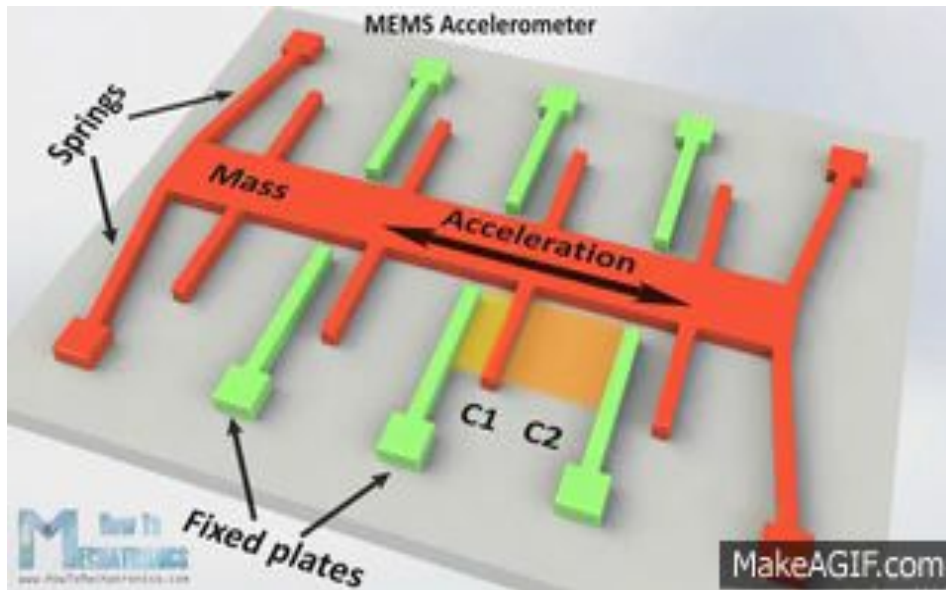




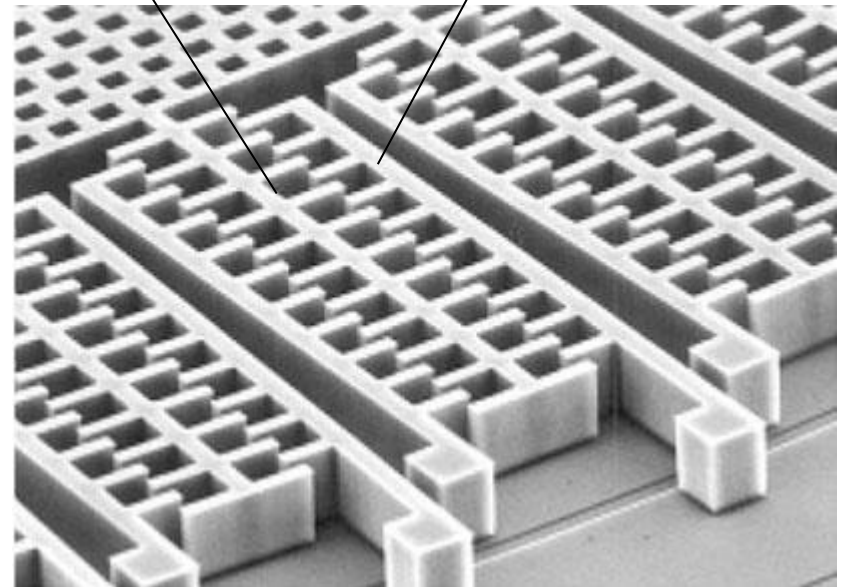
1 / Industrial & automotive

• Accelerometers

- Displacement of the inertial mass



Polysilicon fingers (stationary)
Inertial mass

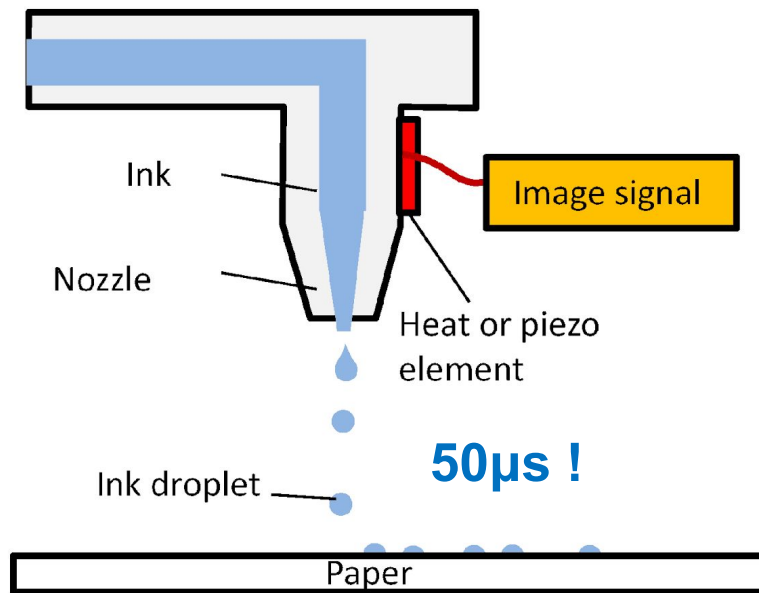




1 / Industrial & automotive

• Nozzles

- Hewlett-Packard (HP)'s thermal inkjet technology (TIT)
- MicroParts' drug-inhaling device for asthma patients ☐ by LIGA process





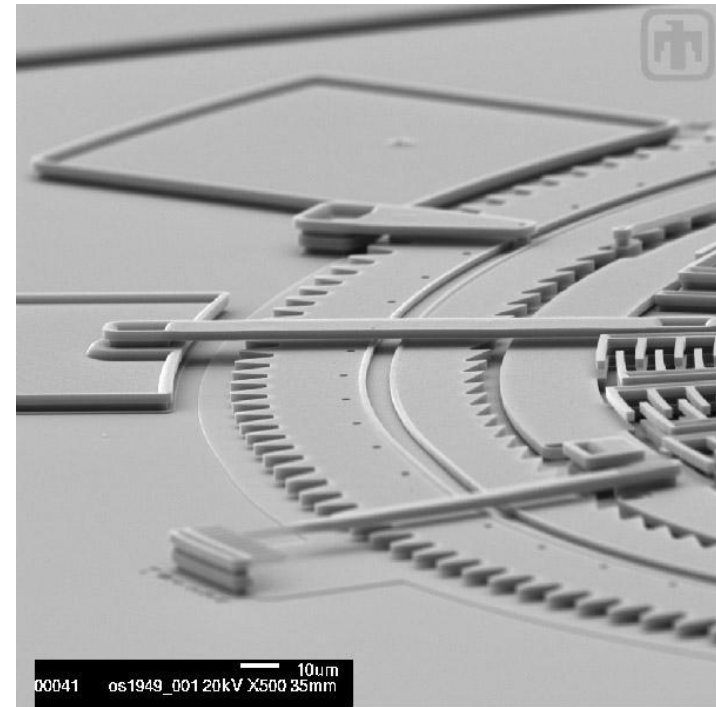
1 / Industrial & automotive

• Nuclear weapons

- Safety devices – stronglinks – have pattern gear discriminators that are fabricated by LIGA process



Detonator pellet





2 / Optical displays

• Texas Instruments' Digital Light Processing (DLP) Technology

- Digital micromirror device (DMD)
- Spatial light modulator/switch

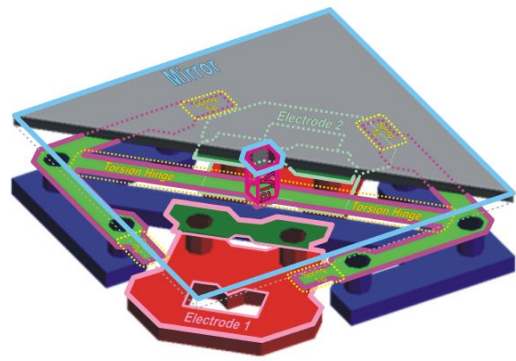
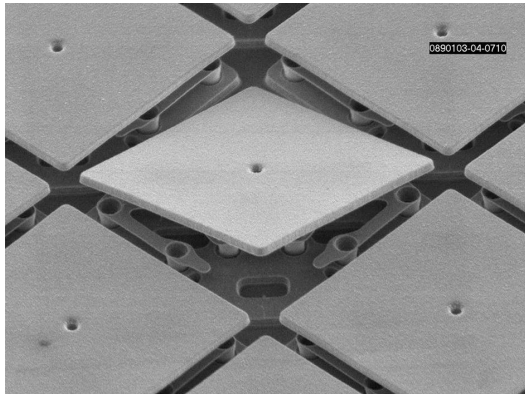
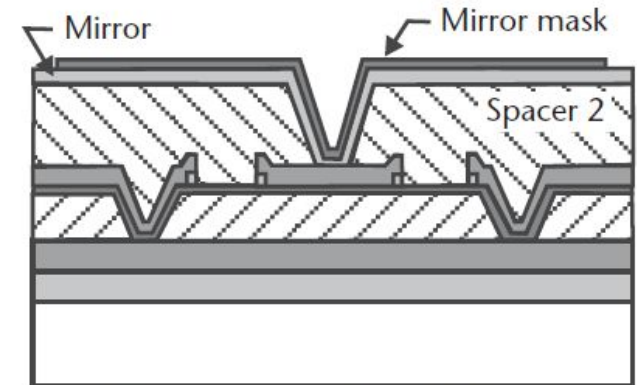
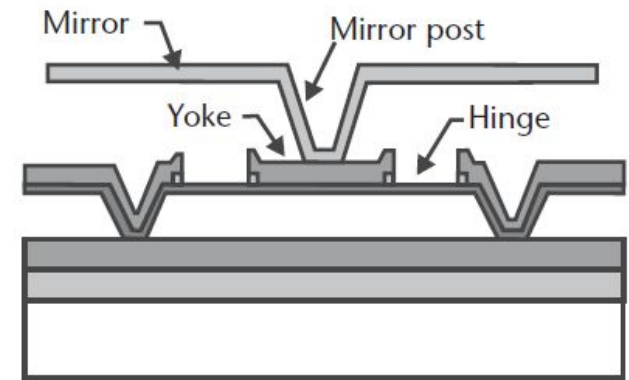


Figure 2. Pixel with Labeled Parts



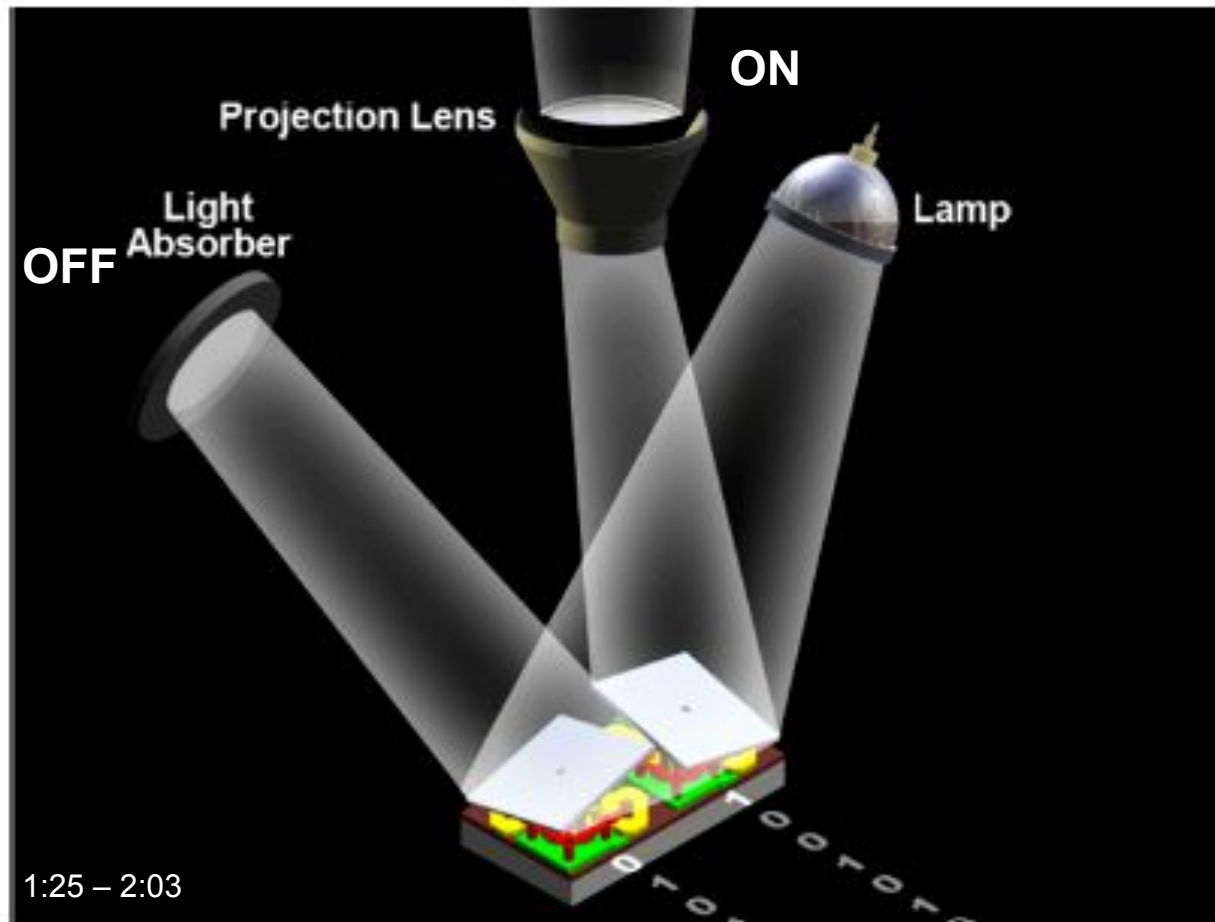
5. Deposit spacer 2 and mirror



6. Pattern mirror and etch sacrificial spacers

- Video – how does it work?

- <http://www.ti.com/general/docs/video/watch.tsp?entryid=5157963226001>



15 μ s – movement of DMD
150 ms – limit of human eye detection

Figure 1. Pixels in On and Off State



2 / Optical displays

- Reliability
 - Hinge fatigue
 - Shock & vibration failure



Outlook for MEMS

Strength

- Provides a customized technical solution for a particular application
- Many tools to choose from

Limitation

- Doesn't have any standards
- Not many high-volume manufacturing applications
 - Absence of “the killer app”
- Diverging demands & fragmentation
- Poor forecasting & investments

To MEMS or not to MEMS?

- Enabling a new function, cost reduction, reliability

***Thank
You***

MEMS



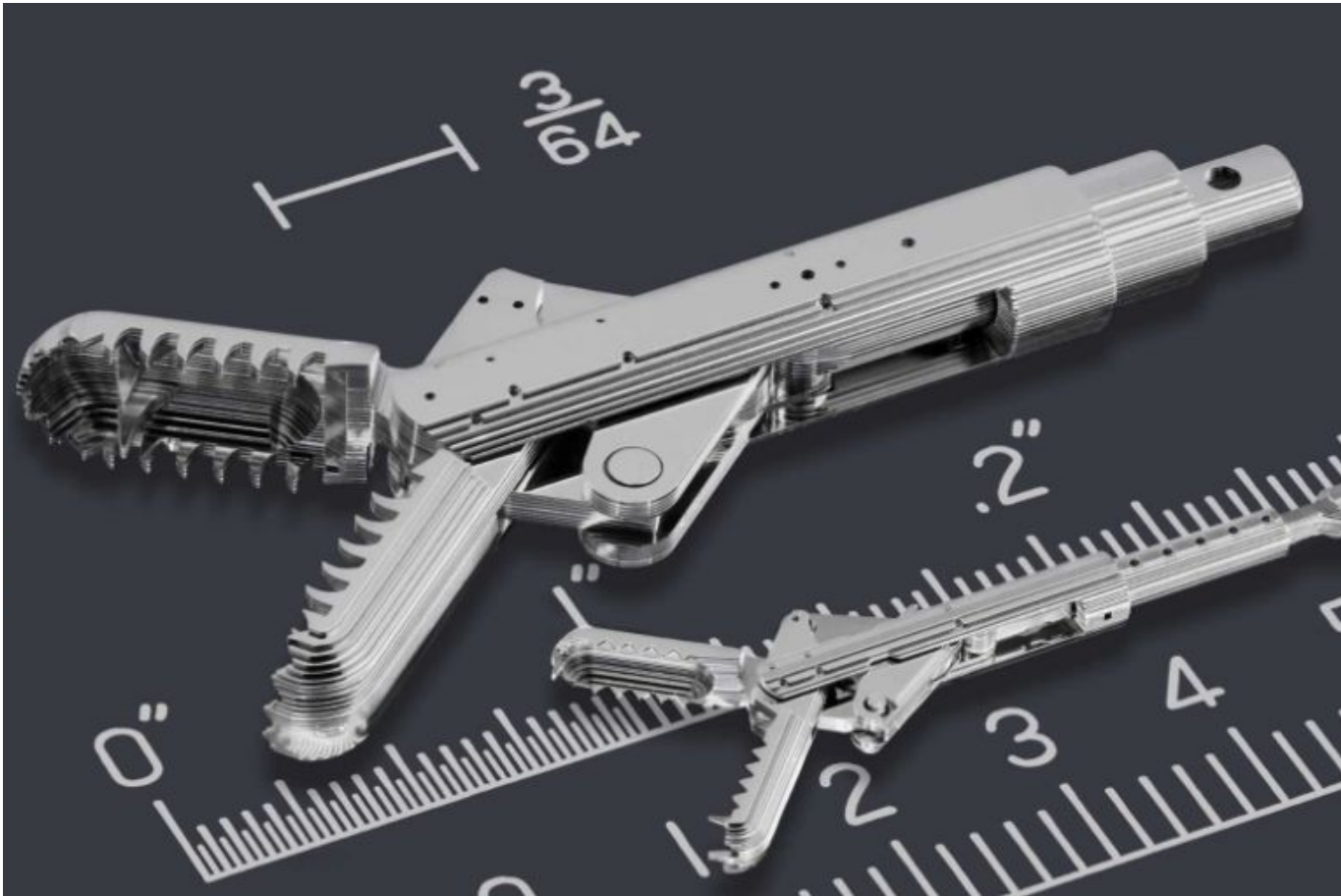


References

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MEMS is evolving ...

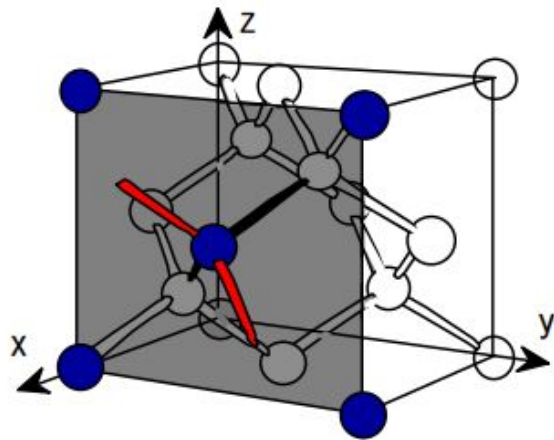


Microfabrica



Miller indices of Silicon

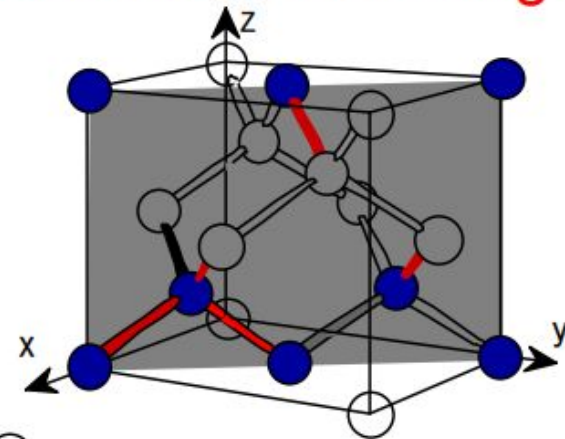
Hypothesis: Number of dangling bond appearing on the silicon surface determines the etching rate



(100)面

Dangling bond: 2

Back bond: 2

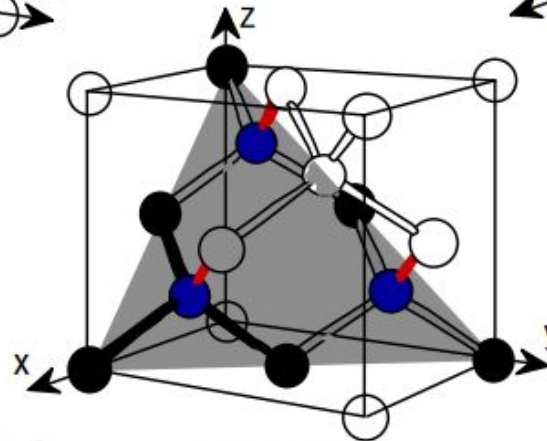


(110)面

Dangling bond: 1 + (2)

(Exposed back bond: 2)

Back bond: 3



(111)面

Dangling bond: 1

Back bond: 3